

## Surface Mount Schottky Barrier Rectifier

Reverse Voltage - 40V

Forward Current - 5.0A

### FEATURES

- Metal silicon junction, majority carrier conduction
- Low power loss, high efficiency
- High forward surge current capability
- For use in low voltage, high frequency inverters, free wheeling, and polarity protection applications

### MECHANICAL DATA

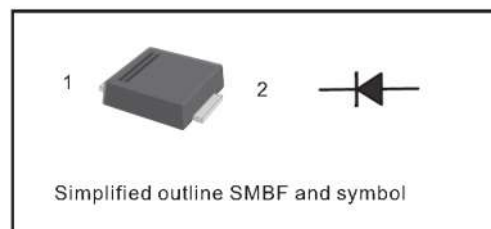
- Case: SMBF
- Terminals: Solderable per MIL-STD-750, Method 2026
- Approx. Weight: 57mg / 0.002oz

### Absolute Maximum Ratings and Electrical characteristics

Ratings at 25°C ambient temperature unless otherwise specified. Single phase, half wave, 60Hz resistive or inductive load, for capacitive load, derate by 20 %

#### PINNING

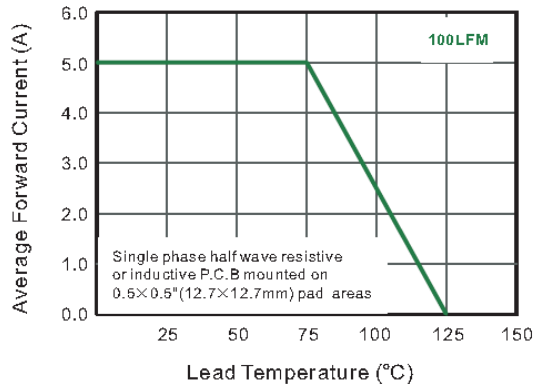
PIN	DESCRIPTION
1	Cathode
2	Anode



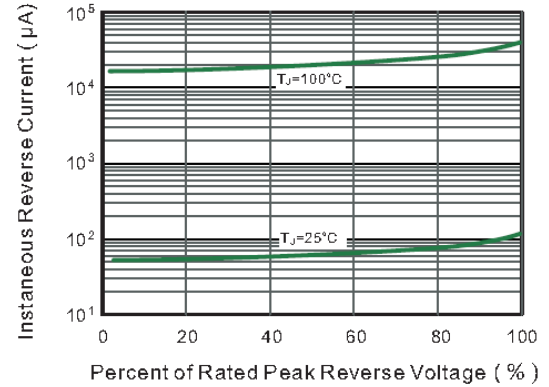
Parameter	Symbols	KSL54BF	Units
Maximum Repetitive Peak Reverse Voltage	$V_{RRM}$	40	V
Maximum RMS voltage	$V_{RMS}$	28	V
Maximum DC Blocking Voltage	$V_{DC}$	40	V
Maximum Average Forward Rectified Current	$I_{F(AV)}$	5.0	A
Peak Forward Surge Current, 8.3ms Single Half Sine-wave Superimposed on Rated Load (JEDEC method)	$I_{FSM}$	160	A
Max Instantaneous Forward Voltage at 5 A	$V_F$	0.50	V
Maximum DC Reverse Current $T_a = 25^\circ\text{C}$ at Rated DC Reverse Voltage $T_a = 100^\circ\text{C}$	$I_R$	1 50	mA
Typical Junction Capacitance <sup>1)</sup>	$C_j$	800	pF
Typical Thermal Resistance <sup>2)</sup>	$R_{\theta JA}$	40	$^\circ\text{C/W}$
Operating Junction Temperature Range	$T_j$	-55 ~ +125	$^\circ\text{C}$
Storage Temperature Range	$T_{sig}$	-55 ~ +150	$^\circ\text{C}$

1) Measured at 1MHz and applied reverse voltage of 4 V D.C. 2) P.C.B. mounted with 0.5 X 0.5" (12.7 X 12.7 mm) copper pad areas.

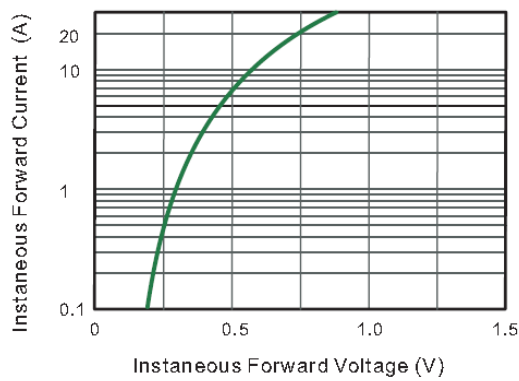
**Fig.1 Forward Current Derating Curve**



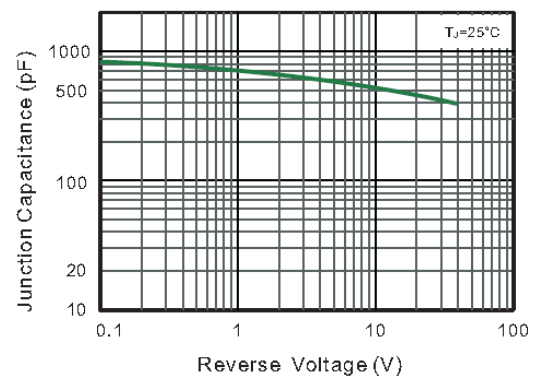
**Fig.2 Typical Reverse Characteristics**



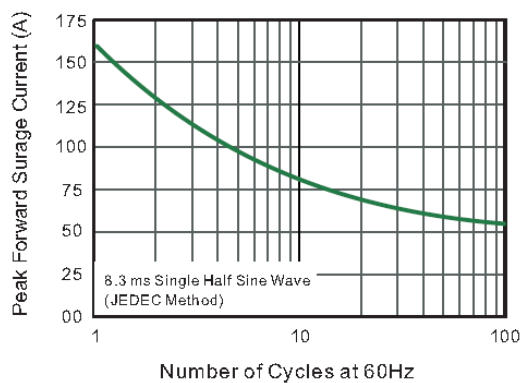
**Fig.3 Typical Forward Characteristic**



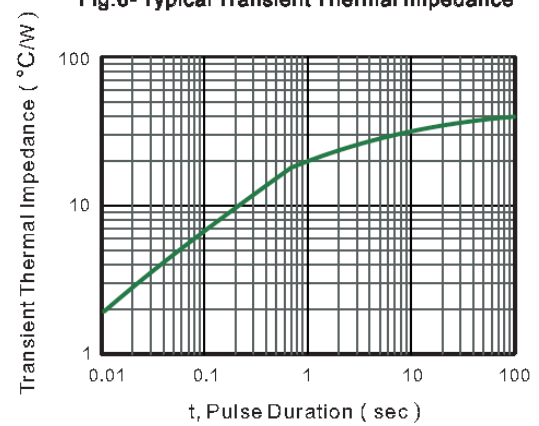
**Fig.4 Typical Junction Capacitance**



**Fig.5 Maximum Non-Repetitive Peak Forward Surge Current**



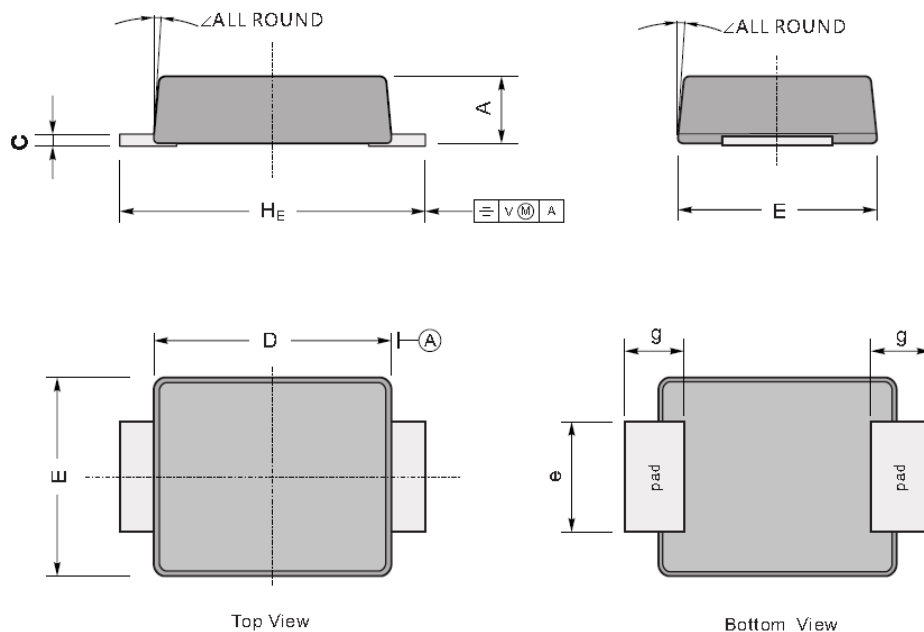
**Fig.6- Typical Transient Thermal Impedance**



## PACKAGE OUTLINE

Plastic surface mounted package; 2 leads

SMBF



UNIT		A	C	D	E	H <sub>E</sub>	e	g	∠
mm	max	1.3	0.26	4.4	3.7	5.5	2.2	1.0	9°
	min	1.1	0.18	4.2	3.5	5.1	1.9		
mil	max	51	10	173	146	216	86	40	
	min	43	7	165	138	200	75		

### The recommended mounting pad size

